

## 1. 2019 년 교육 계획

분기	차수	일시	내용	정원
1/4	47 차	2019.01.17	<u>Basic Course:</u> Microstructures Sample preparation for Metallurgy	10 명
	48 차	2019.02.21	<u>Basic Course:</u> Microstructures Sample preparation for Electronic Materials	10 명
	78 차	2019.03.14	<u>MultiPrep System Users Meeting:</u> Cross-Section/ TEM Wedge Sample Preparation	6 명
2/4	49 차	2019.04.11	<u>Basic Course:</u> Microstructures Sample preparation for Metallurgy	10 명
	50 차	2019.05.16	<u>Basic Course:</u> Microstructures Sample preparation for Electronic Materials	10 명
	79 차	2019.06.13	<u>MultiPrep System Users Meeting:</u> Parallel Thinning for Die & Package Analysis	6 명
3/4	51 차	2019.07.11	<u>Basic Course:</u> Microstructures Sample preparation for Metallurgy	10 명
	52 차	2019.08.22	<u>Basic Course:</u> Microstructures Sample preparation for Electronic Materials	10 명
	80 차	2019.09.19	<u>MultiPrep System Users Meeting:</u> Cross-Section/ TEM Wedge Sample Preparation	6 명
4/4	53 차	2019.10.17	<u>Basic Course:</u> Microstructures Sample preparation for Metallurgy	10 명
	54 차	2019.11.14	<u>Basic Course:</u> Microstructures Sample preparation for Electronic Materials	10 명
	81 차	2019.12.12	<u>MultiPrep System Users Meeting:</u> Parallel Thinning for Die & Package Analysis	6 명